



Integrated Device Technology, Inc.  
 2975 Stender Way, Santa Clara, CA - 95054

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A-0406-06**                      DATE: 7/2/2004  
 Product Affected: SOIC Package Family  
   (DC 8, DCG 8, DCG14, and DCG16)  
 Date Effective: 8/3/2004

MEANS OF DISTINGUISHING CHANGED DEVICES:  
 Product Mark  
 Back Mark         Lot number will have the "C" prefix.  
 Date Code  
 Other

Contact: Geoffrey Cortes  
 Title: Corporate QA / Reliability Manager                      Attachment::  Yes                       No  
 Phone #: (408) 492- 8321  
 Fax #: (408) 727-2328    Samples:                      See attachment  
 E-mail: [Geoffrey.Cortes@idt.com](mailto:Geoffrey.Cortes@idt.com)

**DESCRIPTION AND PURPOSE OF CHANGE:**

- Die Technology
- Wafer Fabrication Process
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site                      OSE- Philippines is a qualified assembly facility for SOIC 14/16 (DC14, DC16) packages. This notification is to advise customers of additional SOIC packages manufacturing at OSE Philippines assembly location. Please see attachment for details.
- Data Sheet
- Other

**RELIABILITY/QUALIFICATION SUMMARY:**

Please see attachment for qualification data.

**CUSTOMER ACKNOWLEDGMENT OF RECEIPT:**

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.  
 IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

**CUSTOMER COMMENTS:** \_\_\_\_\_

**IDT ACKNOWLEDGMENT OF RECEIPT:**

RECD. BY: \_\_\_\_\_                      DATE: \_\_\_\_\_



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### ATTACHMENT - PCN #: A-0406-06

**PCN Type:** Manufacturing Site

**Data Sheet Change:** None

**Detail of Change:** OSE- Philippines is a qualified assembly facility for SOIC 14/16 (DC14, DC16) packages. This notification is to advise customers of additional SOIC packages manufacturing at OSE Philippines assembly location.

No datasheet or Moisture Sensitive Level (MSL) changes are expected due to this assembly site change. Customers are not expected to be adversely impacted by this change.

Description	Manufacturing Site	
	Existing	Add
SOIC Package Family	Amkor Technology Philippines (ATP)	OSE-Phillippines

The affected package types are as follow:

Package Family	Package Type	Top Mark Designator (Part # Ending with)
	DC/DCG8	S, SG, S1, S1G, DC, DCG
	DCG14	S1G, DCG
	DCG16	S1G, DCG

**Note:** For T & R (shipping method) "8" is added to the part number and for industrial grade, letter "I" is added to the part number.

**Samples are not built ahead of the change and are limited to selective devices. Please contact your local field sales representative for sample availability and additional information.**



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## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT - PCN #: A-0406-06

**Qualification Plan #:** P00-02-02

**Test Vehicle:** DC14/DC16

**Qualification Test Plan and Results:**

Test Description	Test Method	Sample Size	Test Results SOIC (DC14) (SS / # of Fails)	Test Results SOIC (DC16) (SS / # of Fails)
* High Accelerated Stress Test (Biased, 130 °C/85% RH, 100 Hrs)	JESD22-A110-B	45/0	45/0	45/0
* Temperature Cycling (-65 °C to 150 °C, 500 cycle)	JESD22-A104-B	45/0	45/0	45/0
* Auto Clave (121 °C, 2 ATM, 168 Hrs)	JESD22-A102-C	45/0	45/0	45/0
Physical Dimensions	JESD22-B100-B	5/0	5/0	5/0
Internal Visual Inspection	MIL-STD-883, M 2010	5/0	5/0	5/0
External Visual Inspection	JESD22-B101	25/0	25/0	25/0
Resistance to Solvents	MIL-STD-883, M 2015	3/0	3/0	3/0
Bake & Ball Shear Test	JESD22-B116	5/0	5/0	5/0
Bond Pull Test	MIL-STD-883, M 2011	5/0	5/0	5/0
S.A.T	J-STD-035	10/0	10/0	10/0
X-ray Examination	MIL-STD-883, M 2015	45/0	45/0	45/0
Moisture Sensitivity Classification (Performed on each package type)	J-STD-020B	2 lots	Pass	Pass

**Notes:** \* Test requires moisture pre-conditioning sequence per JESD22-A113C.  
a. There is no change in moisture sensitivity level.



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### Product List

IDT2305-1DC	IDT2305-1DCGI
IDT2305-1DCI	IDT2305-1HDCG
IDT2305-1HDC	IDT2305-1HDCGI
IDT2305-1HDCI	IDT2305A-1DCG
IDT2305A-1DC	IDT2305A-1DCGI
IDT2305A-1DCI	IDT2305A-1HDCG
IDT2305A-1HDC	IDT2305A-1HDCGI
IDT2305A-1HDCI	IDT2308-2DCG
IDT23S05-1DC	IDT2308-2DCGI
IDT23S05-1DCI	IDT2308A-1HDCG
IDT23S05-1HDC	IDT2308A-1HDCGI
IDT23S05-1HDCI	IDT2309-1HDCG
IDT23S05E-1DC	IDT2309-1HDCGI
IDT23S05E-1DCI	IDT2309A-1HDCG
IDT23S05E-1HDC	IDT2309A-1HDCGI
IDT23S05E-1HDCI	IDT23S05-1DCG
IDT23S05T-1DC	IDT23S05-1DCGI
IDTNW6000AS	IDTQS3253S1G
IDTQS3306AS1	IDTQS3257S1G
IDTSP306DC	IDTQS3VH125S1G
IDT2305-1DCG	

**Note:** For T & R (shipping method) "8" is added to the part number.